
PACKAGING OF NON-ELECTROSTATIC DISCHARGE SENSITIVE (NON-ESDS) DEVICES, PARTS AND COMPONENT ASSEMBLIES

1.0 SCOPE

This standard provides methods for the protection of solid state devices parts/components.

NOTE

This document supersedes/replaces LMSC Packaging Standards P-19F and P-74E.

IMPORTANT

SUPPLIERS ARE REQUESTED TO REVIEW THE SPECIFIC ITEMS METHOD OF PACKAGING (SEE PARAGRAPH 3.0, AS APPLICABLE), AND THE MATERIAL REQUIREMENTS SPECIFIED (SEE PARAGRAPH 5.0), AND USE THE PROPER TYPE(S) OF PACKAGES/MATERIALS, TO MEET THE REQUIREMENTS OF THIS STANDARD.

CAUTION

PACKAGES THAT DO NOT CONFORM TO THE REQUIREMENTS OF THIS STANDARD ARE SUBJECT TO REJECTION AND RETURN TO THE SUPPLIER AT THE SUPPLIER'S EXPENSE.

2.0 REFERENCES

2.1 LMSC DOCUMENTS

2.1.1 LPS 40-001, LMSC Packaging Standard, "General Requirements Specification"

2.2 GOVERNMENT/MILITARY DOCUMENTS

2.2.1 MIL-M-55565, "Microcircuits, Packaging of"

2.2.2 MIL-S-19500, "Semiconductor Devices, General Specification for"

2.2.3 MIL-R-39032, "Resistors, Packaging of"

2.2.4 MIL-S-19491, "Semiconductor Devices, Packaging of"

2.2.5 MIL-M-38510, "Microcircuits, General Specification for"

2.2.6 MIL-STD-129, "Marking for Shipment and Storage"

3.0 REQUIREMENTS

3.1 GENERAL

NOTE

- Use of carbon loaded materials is not allowed due to their contaminating qualities.
- If requested by LMSC, suppliers must produce written certification of compliance of required materials conforming to this specification.

3.1.1 The requirements of LPS 40-001 shall be met in addition to provisions of this packaging standard.

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3.2 DEVICE/PACKAGING INDEX

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